

Application Memo

Tin in Plating Liquid for Soldering

Industry	Nonferrous metal
Instrument	Automatic potentiometric titrator
Measurement method	Redox titration
Standards	

1. Overview

Tin (Sn^{2+}) in plating liquid for soldering is measured by titration with 0.05mol/L iodine solution after the sample is added with 50% HCl and sodium hydrogen carbonate. The endpoint is the maximum inflexion on the titration curve. The tin concentration is calculated from the titration volume of the iodine solution.

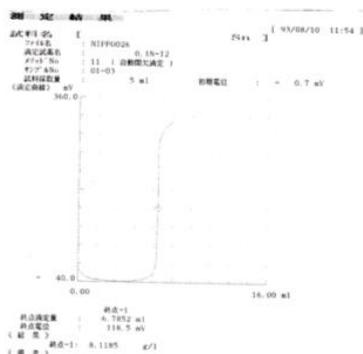
2. Apparatus

Main unit	Automatic potentiometric titrator (preamplifier STD)
Electrode	Platinum electrode Ceramic reference electrode

3. Reagents

Titrant	0.05mol/L (0.1N) iodine ($f = 1.008$)
Solvent	50% hydrochloric acid, Sodium hydrogen carbonate

4. Example



—Titration curve—

—Measurement results—

	Sample (mL)	Titer (mL)	Tin (g/L)
1	5.0	6.7852	8.119

Please feel free to contact us for any further information.
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